



Product/Process Change Notification Form

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| PCN Number: | PCN-2014-0487 |
| Date of Notification: | 7/16/2014 |
| Apex P/N(s): | SA09, SA12, SA12-13 |
| Date PCN Effective: | 10/1/2014 |
| Reason for Change: | <input type="checkbox"/> Design /New Rev. <input type="checkbox"/> Assembly Site <input checked="" type="checkbox"/> Assembly Process <input type="checkbox"/> Other (specify) Internal semiconductor chip thickness variation |
| Description of Change: | The temperature sense devices are now mounted directly to the top surface of the MOSFET output devices. |
| Apex P/N Change: | <input type="checkbox"/> Yes, New Part Number: <input checked="" type="checkbox"/> No |
| Lot Effective Date: | 10/1/14 |
| Quality & Reliability impact: | Qualification Data: <input type="checkbox"/> Required <input checked="" type="checkbox"/> Not Required |
| Datasheet Change Required? | <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No If Yes, briefly explain: |